

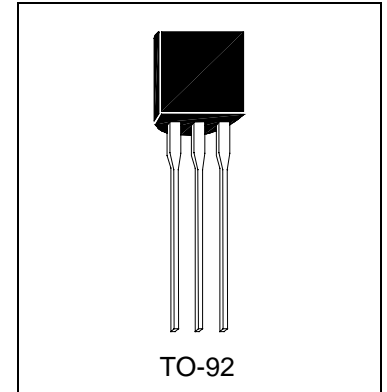


# HTL195

PNP EPITAXIAL PLANAR TRANSISTOR

## Description

The HTL195 is designed for high voltage low power switching applications especially for use in telephone and telecommunication circuits.



## Absolute Maximum Ratings

- Maximum Temperatures  
 Storage Temperature ..... -55 ~ +150 °C  
 Junction Temperature ..... 150 °C Maximum
- Maximum Power Dissipation  
 Total Power Dissipation (Ta=25°C) ..... 1 W
- Maximum Voltages and Currents (Ta=25°C)  
 VCBO Collector to Base Voltage ..... -500 V  
 VCEO Collector to Emitter Voltage ..... -500 V  
 IC Collector Current ..... -300 mA

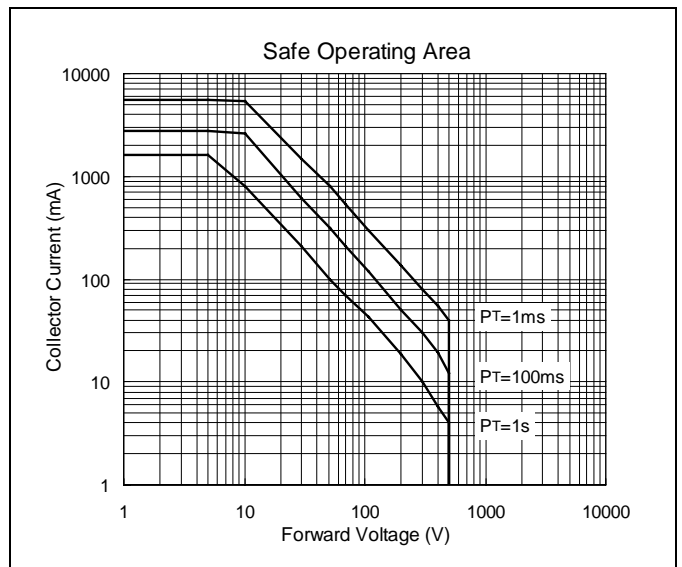
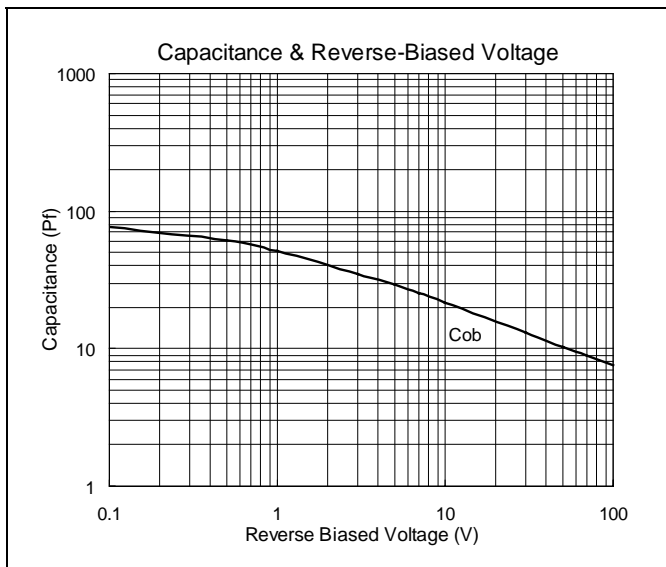
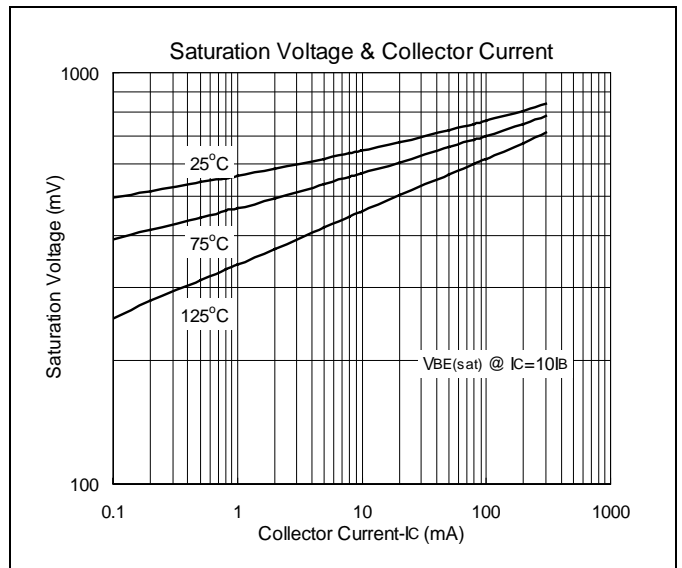
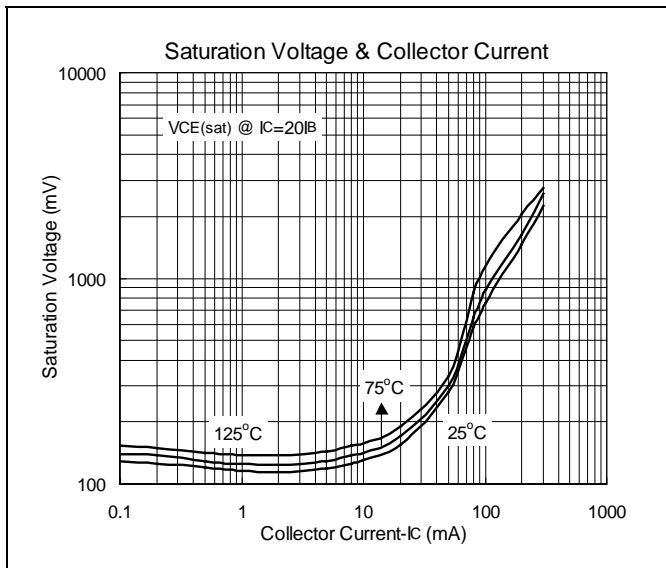
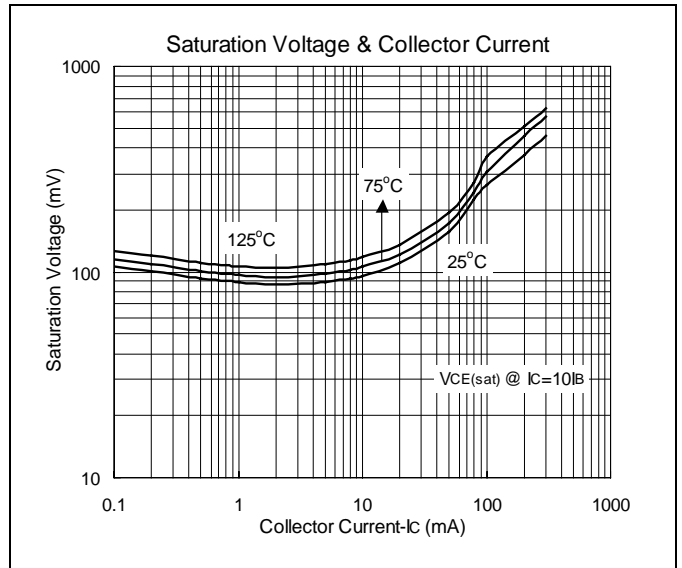
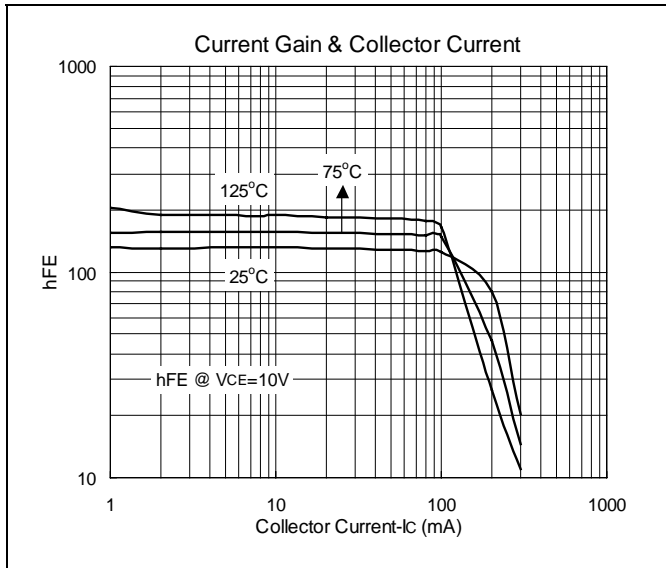
## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-500	-	-	V	IC=-100uA, IE=0
BVCEO	-500	-	-	V	IC=-1mA, IB=0
ICBO	-	-	-10	uA	VCB=-500V, IE=0
ICEO	-	-	-1	uA	VCE=-100V, IB=0
IEBO	-	-	-200	nA	VEB=-6V, IC=0
*VCE(sat)1	-	-	-500	mV	IC=-20mA, IB=-2mA
*VCE(sat)2	-	-	-3	V	IC=-80mA, IB=-4mA
*VBE(sat)	-	-	-900	mV	IC=-20mA, IB=-2mA
*hFE1	50	-	-		VCE=-10V, IC=-1mA
*hFE2	50	-	300		VCE=-10V, IC=-20mA
*hFE3	40	-	-		VCE=-10V, IC=-80mA
fT	10	-	-	MHz	VCE=-20V, IE=-10mA, f=1MHz
Cob	-	-	30	pF	VCB=-20V, f=1MHz, IE=0

\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

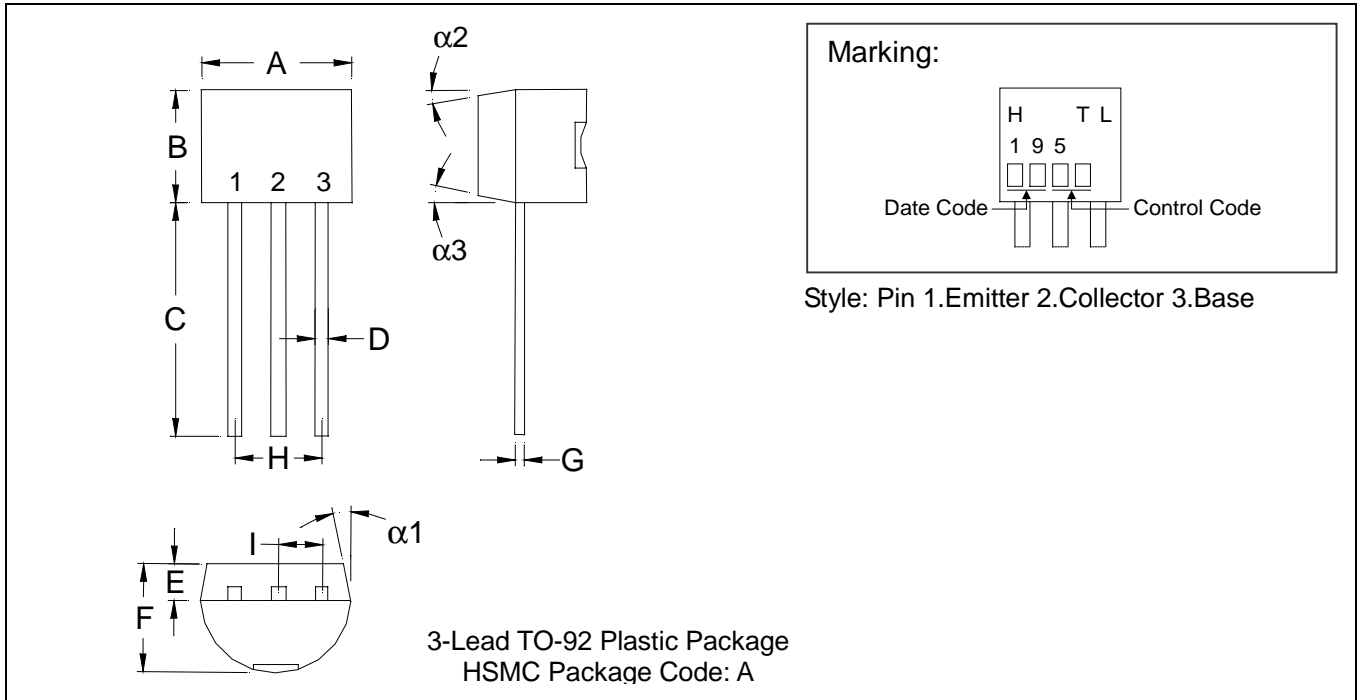


### Characteristics Curve





### TO-92 Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

Notes: 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.  
 2.Controlling dimension: millimeters.  
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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